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CERMET PLATINUM PALLADIUM SILVER CONDUCTOR

9562

ESL 9562 is a low cost wire bondable PtPdAg. It exhibits excellent solderability and adhesion with good aged bond retention. ESL 9562 can be used as a termination for 850°C fired resistor series.

PASTE DATA

RHEOLOGY:	Thixotropic, screen printable paste
VISCOSITY: (Brookfield RVT, ABZ Spindle, 10 rpm, 25.5°C±0.5°C)	185±15 Pa·s
BONDING MECHANISM:	MICRO-LOK®
SHELF LIFE: (25°C)	6 months

PROCESSING

SCREEN MESH/EMULSION:	325/25 µm
LEVELING TIME: (25°C)	5-10 minutes
DRYING AT 125°C:	10-15 minutes
FIRING RANGE:	850°C-930°C
OPTIMUM:	930°C
TIME AT PEAK:	10-12 minutes
RATE OF ASCENT/DESCENT:	60°C-100°C/minute
SUBSTRATE OF CALIBRATION:	96% alumina
THINNER:	ESL 401

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ESL Affiliates

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TYPICAL PROPERTIES

FIRED THICKNESS:	12.5±2.5 µm
COVERAGE:	90-100 cm ² /g
RESISTIVITY:	6 mΩ/square
PRINTING RESOLUTION: (Line/Space)	250 µm x 250 µm
SOLDER WETTABILITY: (RMA flux, 5 sec. dip) (62 Sn/36 Pb/2 Ag, 220°C ± 5°C)	very good
(63 Sn/37 Pb, 250°C±5°C)	good
SOLDER LEACH: (No. of 10 sec. dip to double resistance of 0.25 mm wide x 100 mm long conductor, 62 Sn/36 Pb/2 Ag, 220°C±5°C)	6-12
ADHESION: (90° pull, 2.0 mm x 2.0 mm pads, 62 Sn/36 Pb/2 Ag)	
Initial pull strength:	> 44 N
Aged 48 hours at 150°C:	26-44 N
ULTRASONIC WIRE BOND: (25 µm Al wire)	8-10 grams
THERMOSONIC WIRE BOND: (25 µm Au wire)	5-8 grams
MIGRATION RESISTANCE:	fair to poor
	Excellent when protected with ESL 4904 or similar overglaze
COMPATIBILITY:	MULTILAYER DIELECTRIC 4905-C
	RESISTORS ESL 3900 Series
	SOLDER PASTE ESL 3701

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CAUTION: Proper industrial safety precautions should be exercised in using these products. Use with adequate ventilation. Avoid prolonged contact with skin or inhalation of any vapors emitted during use or heating of these compositions. The use of safety eye goggles, gloves or hand protection creams is recommended. Wash hands or skin thoroughly with soap and water after using these products. Do not eat or smoke in areas where these materials are used. Refer to appropriate MSDS sheet.

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